Multilayer Ceramic Chip Capacitors

C2012X7S0J156M125AC

Recommended Land Pattern (PC)







1 of 3 Creation Date : May 22, 2017 (GMT)



TDK item description C2012X7S0J156MT****

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C2012 [EIA 0805]	
Status	Production	



Size Size		
Length(L)	2.00mm ±0.20mm	
Width(W)	1.25mm ±0.20mm	
Thickness(T)	1.25mm ±0.20mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)	0.50mm Min.	
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)	
Recommended Land Fattern (FA)	0.90mm to 1.20mm(Reflow Soldering)	
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)	
Recommended Land Fattern (FB)	0.70mm to 0.90mm(Reflow Soldering)	
D	0.80mm to 1.10mm(Flow Soldering)	

Electrical Characteristics		
Capacitance	15μF ±20%	
Rated Voltage	6.3VDC	
Temperature Characteristic	X7S(±22%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	6ΜΩ	

0.90mm to 1.20mm(Reflow Soldering)

Other	
Coldoring Mothod	Wave (Flow)
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

C2012X7S0J156M125AC

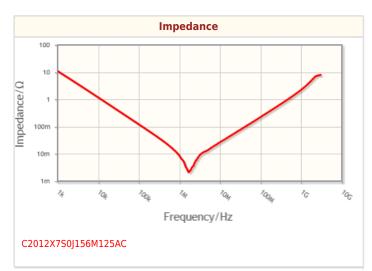


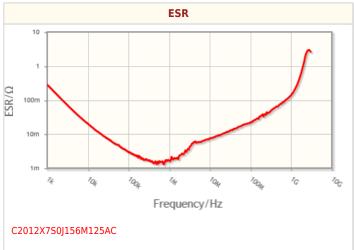


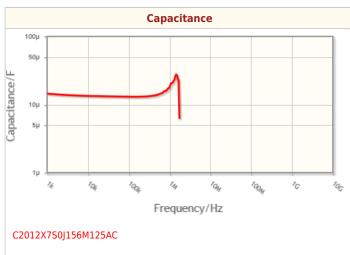


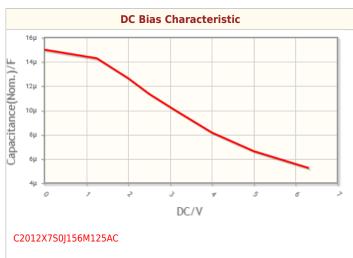


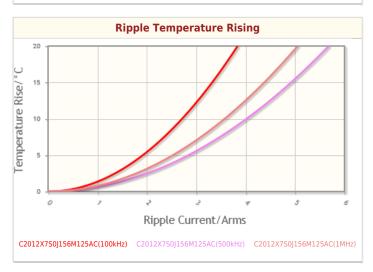
$Characteristic\ Graphs (This\ is\ reference\ data,\ and\ does\ not\ guarantee\ the\ products\ characteristics.)$











[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.



C2012X7S0J156M125AC

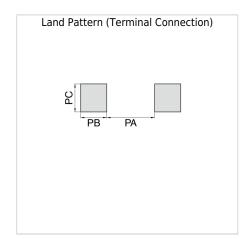








Associated Images



[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.